

50 Watts • 50 Volts • 300us, 10% 1200-1400 MHz

E Series Earless/Eared GaN Transistor – Key Features

- 1200-1400MHz, 50W Output Power at 300µS, 10% pulsing
- 50V Bias Voltage, Common Source, Class AB
- >60% Typical Efficiency Across the Frequency Band
- Extremely Compact Size
- Over 16dB typical Power Gain
- Excellent Gain Flatness
- Radar, L-Band Avionics, Communications, and Industrial applications
- · All gold metallization and eutectic die attach for highest reliability
- 50Ω in/out lumped element very small footprint plug & play pallets available

ABSOLUTE MAXIMUM RATINGS

Maximum Power Dissipation

Device Dissipation @ 25°C 100 W

Maximum Voltage and Current

Drain-Source Voltage (VDSS) 150 V Gate-Source Voltage (VGS) -8 to +0 V

Maximum Temperatures

Storage Temperature (TSTG) -55 to +125° C

Operating Junction Temperature +200 °C

CASE OUTLINE 55-QQP/QQ/Pallet Common Source







ELECTRICAL CHARACTERISTICS @ 25°C

Symbol	Characteristics	Test Conditions	Min	Тур	Max	Units
Роит	Output Power	P _{IN} =1.6W, Freq=1200,1300,1400MHz	50	58		W
G _P	Power Gain	P _{IN} =1.6W, Freq=1200,1300,1400MHz	15.2	15.9		dB
η _D	Drain Efficiency	P _{IN} =1.6W, Freq=1200,1300,1400MHz	55	60		%
Dr	Droop	P _{IN} =1.6W, Freq=1200,1300,1400MHz		0.2	0.6	dB
VSWR-T	Load Mismatch Tolerance	Po=50W, Freq=1300MHz, 300µs-10%			5:1	

• Bias Condition: Vdd=+50V, Idq=20mA constant current (Vgs= -2.0 ~ -4.5V typical)

FUNCTIONAL CHARACTERISTICS @ 25°C

$I_{D(Off)}$	Drain leakage current	V _{GS} = -8V, V _D = 150V		4	mA
I _{G(Off)}	Gate leakage current	$V_{GS} = -8V$, $V_D = 0V$		0.5	mA

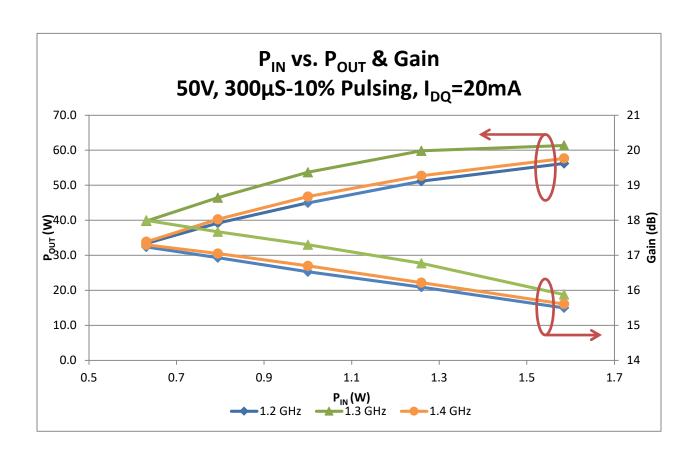
Export Classification: EAR-99



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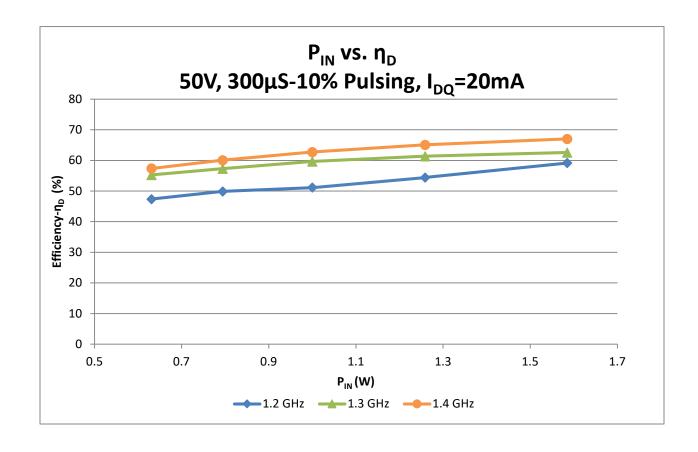
Typical Data

	50V, 300μS-10% Pulsing, IDQ=20mA								
Freq (GHz)	P _{IN} (dBm)	P _{IN} (W)	Р _{оит} (dBm)	Р _{оит} (W)	Gain (dB)	IRL (dB)	I _D (A)	Droop (dB)	Eff η _D (%)
1.2	32	1.6	47.5	56.2	15.5	-8	0.21	0.3	59%
1.3	32	1.6	47.9	61.4	15.9	-18	0.216	0.25	63%
1.4	32	1.6	47.6	57.7	15.6	-7.6	0.192	0.2	67%





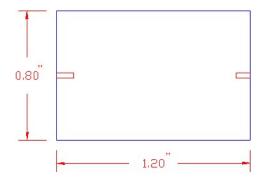
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1214GN-50E/EL Test Fixture Overall Dimension



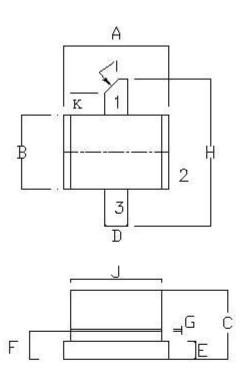
(Dimensions shown are in inches)

Evaluation Test Fixture available upon request



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55-QQP PACKAGE DIMENSION



Dim	Millimeter	Tol	Inches	Tol
Α	5.84	.25	.230	.010
В	4.06	.25	.160	.010
С	3.17	.05	.125	.002
D	1.27	.13	.050	.005
E	1.02	.13	.040	.005
F	1.57	.13	.062	.005
G	.130	.02	.005	.001
H	8.12	.25	.320	.010
1	45°	5°	45°	5°
J	5.08	.25	.200	.010
K	1.40	.13	.055	.005

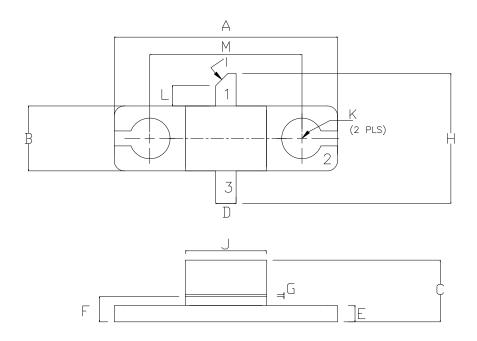
PIN 1: DRAIN PIN 2: SOURCE PIN 3: GATE





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55-QQ PACKAGE DIMENSION



Dim	Millimeter	Tol	Inches	Tol	
Α	13.970	0.250	0.550	0.010	
В	4.570	0.250	0.160	0.010	
С	3.860	0.330	0.152	0.013	
D	1.270	0.130	0.050	0.005	
E	1.020	0.130	0.040	0.005	
F	1.700	0.130	0.067	0.005	
G	0.130	0.025	0.005	0.001	
Н	8.130	0.250	0.320	0.010	
1	45°	5°	45°	5°	
J	5.080	0.250	0.200	0.010	
K	2.54 DIA	0.130	.100 DIA	0.005	
L	1.270	0.130	0.050	0.005	
M	9.530	0.130	0.375	0.005	

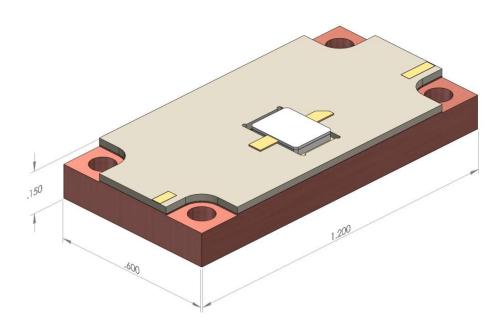






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90-1214GN-50EP OVERALL PALLET DIMENSION



Dimension 1.2" X.6"X.15"



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Revision History

Revision Level / Date	Para. Affected	Description
0.1 / 22 August 2016	•	Initial Preliminary Release